

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32G051C6U6	72MI*456XXXZ	A	998Z	2023-11-05
	Amount	UoM	Unit type	ST ECOPACK Grade
	102.55	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	7x7x0.55	48	flat	
Comment	Package : A0B9 UQFPN 7X7X0.55 48L 0.5 MM PITCH 8202210			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	72MI*456XXXZ				5999999.0	1000000.6				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	1.692	mg	supplier	die	Silicon (Si)	7440-21-3		1.531	mg	904846	14929				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.008	mg	4728	78				
				supplier	metallization	Copper (Cu)	7440-50-8		0.068	mg	40189	663				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.022	mg	13002	215				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	591	10				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	591	10				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.017	mg	10047	166				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.044	mg	26005	429				
				Glue epoxy (EN4900GC)	M-011 Other inorganic materials	0.566	mg	Supplier	Organic Compounds	Acrylic resin	Trade Secret		0.040	mg	70000	387
								Supplier	Organic Compounds	Polybutadiene derivative	Trade Secret		0.011	mg	20000	110
Supplier	Organic Compounds	Butadiene copolymer	Trade Secret						0.008	mg	15000	83				
Supplier	Organic Compounds	Acrylate	Trade Secret						0.031	mg	54000	298				
Supplier	Organic Compounds	Epoxy resin	Trade Secret						0.017	mg	30000	166				
Supplier	Organic Compounds	Peroxide	Trade Secret						0.005	mg	8000	44				
Supplier	Organic Compounds	Additive	Trade Secret						0.010	mg	18000	99				
Supplier	Metals	Silver	7440-22-4						0.445	mg	785000	4335				
Encapsulation (EME-G770)	M-011 Other inorganic materials	37.148	mg					Supplier	Plastics/polymers	Epoxy Resin A	Trade Secret		0.780	mg	21000	7607
								Supplier	Plastics/polymers	Epoxy Resin B	Trade Secret		0.780	mg	21000	7607
				Supplier	Plastics/polymers	Phenol Resin A	Trade Secret		0.780	mg	21000	7607				
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		28.992	mg	780450	282713				
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		4.284	mg	115320	41774				
				Supplier	Non-metals	Carbon Black	1333-86-4		0.231	mg	6230	2257				
				Supplier	Metals Compounds	Metal Hydroxide	Trade Secret		0.520	mg	14000	5071				
				Supplier	Plastics/polymers	Phenol Resin B	Trade Secret		0.780	mg	21000	7607				
Bonding wires (Au)	Bonding Wire	0.864	mg	Supplier	Metals	Gold	7440-57-5		0.864	mg	1000000	8430				
Plating (Sn)	M-011 Other inorganic materials	1.078	mg	Supplier	Metals	Tin	7440-31-5		1.078	mg	1000000	10516				
Leadframe (C7025 + Ag)	Copper & its alloys	61.200	mg	Supplier	Metals	Copper	7440-50-8		56.129	mg	917140	547339				
				Supplier	Metals	Nickel	7440-02-0		1.377	mg	22500	13428				
				Supplier	Metals	Silicon	7440-21-3		0.159	mg	2600	1552				
				Supplier	Metals	Magnesium	7439-95-4		0.070	mg	1150	686				
				Supplier	Metals	Silver	7440-22-4		3.465	mg	56610	33784				